

**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q81505

Akira BANDO, et al.

Appln. No.: 10/585,744

Group Art Unit: 2811

Confirmation No.: 1506

Examiner: Not Yet Assigned

Filed: July 12, 2006

For: N-TYPE GROUP III NITRIDE SEMICONDUCTOR LAYERED STRUCTURE

**REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT**

**ATTN:** Office of Initial Patent Examination  
Filing Receipt Correction  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

We enclose a copy of the Official Filing Receipt for the above-identified application and request the following correction:

**Assignment For Published Patent Application**

**SHOWA DENKO K.K**

Verification for the requested correction is indicated on the U.S. Assignment filed July 12, 2008.

Respectfully submitted,



Abraham J. Rosner  
Registration No. 33,276

SUGHRUE MION, PLLC  
Telephone: (202) 293-7060  
Facsimile: (202) 293-7860

WASHINGTON OFFICE

**23373**

CUSTOMER NUMBER

Date: 7/18/08



# UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE  
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APPLICATION NUMBER	FILING or 371(c) DATE	GRP ART UNIT	FIL FEE REC'D	ATTY.DOCKET.NO	TOT CLAIMS	IND CLAIMS
10/585,744	07/12/2006	2811	1500	Q81505	32	1

CONFIRMATION NO. 1506

## FILING RECEIPT



23373  
SUGHRUE MION, PLLC  
2100 PENNSYLVANIA AVENUE, N.W.  
SUITE 800  
WASHINGTON, DC 20037

# DOCKETED

Date Mailed: 06/16/2008

JUN 17 2008

Receipt is acknowledged of this non-provisional patent application. The application will be taken up for examination in due course. Applicant will be notified as to the results of the examination. Any correspondence concerning the application must include the following identification information: the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. **If an error is noted on this Filing Receipt, please submit a written request for a Filing Receipt Correction. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections**

### Applicant(s)

Akira Bandoh, Chiba, JAPAN;  
Hiromitsu Sakai, Chiba, JAPAN;  
Masato Kobayakawa, Chiba, JAPAN;  
Mineo Okuyama, Chiba, JAPAN;  
Hideki Tomozawa, Chiba, JAPAN;  
Hisayuki Miki, Chiba, JAPAN;  
Joseph Gaze, Chiba, JAPAN;  
Syunji Horikawa, Tokyo, JAPAN;  
Tetsuo Sakurai, Chiba, JAPAN;

**ASSIGNMENT FOR ABOLISHED PATENT APPLICATION**  
**SHOWA DENKO K.K.**

**Power of Attorney:** The patent practitioners associated with Customer Number 23373

### Domestic Priority data as claimed by applicant

This application is a 371 of PCT/JP05/08461 04/27/2005  
which claims benefit of 60/570,135 05/12/2004  
and claims benefit of 60/585,919 07/08/2004

### Foreign Applications

JAPAN 2004-131617 04/27/2004  
JAPAN 2004-153709 05/24/2004  
JAPAN 2004-165406 06/03/2004  
JAPAN 2004-193744 06/30/2004  
JAPAN 2004-213423 07/21/2004  
JAPAN 2005-031374 02/08/2005

**If Required, Foreign Filing License Granted: 06/12/2008**

The country code and number of your priority application, to be used for filing abroad under the Paris Convention, is **US 10/585,744**

**Projected Publication Date: 09/25/2008**

**Non-Publication Request: No**

**Early Publication Request: No**  
**Title**

N-Type Group III Nitride Semiconductor Layered Structure

**Preliminary Class**

257

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# U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter "ASSIGNOR") by

(Insert  
ASSIGNEE's  
Name(s)  
Address(es))

SHOWA DENKO K.K.

13-9, Shibadaimon 1-chome, Minato-ku, Tokyo 1058518, Japan

(hereinafter "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of  
Invention)

N-TYPE GROUP I I I NITRIDE SEMICONDUCTOR LAYERED STRUCTURE

relating to International Patent Application PCT/JP 2005/008461 and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(Insert date  
of execution  
of application,  
if not  
concurrent)

(a) executed on \_\_\_\_\_ ;

(b) filed on \_\_\_\_\_ ,  
Serial No. \_\_\_\_\_ / \_\_\_\_\_ ;

( \_\_\_\_\_ ) is hereby authorized to insert in (b) the specified data, when known.

and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

1) <u>Akira Bandoh</u> (SIGNATURE)	Akira Bandoh (TYPE NAME)	March 1, 2006 (DATE)
2) <u>Hiromitsu Sakai</u> (SIGNATURE)	Hiromitsu Sakai (TYPE NAME)	March 1, 2006 (DATE)
3) <u>Masato Kobayakawa</u> (SIGNATURE)	Masato Kobayakawa (TYPE NAME)	March 1, 2006 (DATE)
4) <u>Mineo Okuyama</u> (SIGNATURE)	Mineo Okuyama (TYPE NAME)	March 1, 2006 (DATE)

- |     |                                       |                                       |                                |
|-----|---------------------------------------|---------------------------------------|--------------------------------|
| 5)  | <u>Hideki Tomozawa</u><br>(SIGNATURE) | <u>Hideki Tomozawa</u><br>(TYPE NAME) | <u>March 1, 2006</u><br>(DATE) |
| 6)  | <u>Hisayuki Miki</u><br>(SIGNATURE)   | <u>Hisayuki Miki</u><br>(TYPE NAME)   | <u>March 1, 2006</u><br>(DATE) |
| 7)  | <u>Joseph Gaze</u><br>(SIGNATURE)     | <u>Joseph Gaze</u><br>(TYPE NAME)     | <u>March 1, 2006</u><br>(DATE) |
| 8)  | <u>Syunji Horikawa</u><br>(SIGNATURE) | <u>Syunji Horikawa</u><br>(TYPE NAME) | <u>March 1, 2006</u><br>(DATE) |
| 9)  | <u>Tetsuo Sakurai</u><br>(SIGNATURE)  | <u>Tetsuo Sakurai</u><br>(TYPE NAME)  | <u>March 1, 2006</u><br>(DATE) |
| 10) | _____<br>(SIGNATURE)                  | _____<br>(TYPE NAME)                  | _____<br>(DATE)                |
| 11) | _____<br>(SIGNATURE)                  | _____<br>(TYPE NAME)                  | _____<br>(DATE)                |
| 12) | _____<br>(SIGNATURE)                  | _____<br>(TYPE NAME)                  | _____<br>(DATE)                |
| 13) | _____<br>(SIGNATURE)                  | _____<br>(TYPE NAME)                  | _____<br>(DATE)                |
| 14) | _____<br>(SIGNATURE)                  | _____<br>(TYPE NAME)                  | _____<br>(DATE)                |
| 15) | _____<br>(SIGNATURE)                  | _____<br>(TYPE NAME)                  | _____<br>(DATE)                |
| 16) | _____<br>(SIGNATURE)                  | _____<br>(TYPE NAME)                  | _____<br>(DATE)                |
| 17) | _____<br>(SIGNATURE)                  | _____<br>(TYPE NAME)                  | _____<br>(DATE)                |
| 18) | _____<br>(SIGNATURE)                  | _____<br>(TYPE NAME)                  | _____<br>(DATE)                |
| 19) | _____<br>(SIGNATURE)                  | _____<br>(TYPE NAME)                  | _____<br>(DATE)                |
| 20) | _____<br>(SIGNATURE)                  | _____<br>(TYPE NAME)                  | _____<br>(DATE)                |